

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Huan Tsai</td> <td>07/26/2004</td> </tr> <tr> <td>Hun-Jan Tao</td> <td>07/26/2004</td> </tr> <tr> <td>Tsang-Jiuh Wu</td> <td>07/26/2004</td> </tr> <tr> <td>Ju-Wang Hsu</td> <td>07/26/2004</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Huan Tsai	07/26/2004	Hun-Jan Tao	07/26/2004	Tsang-Jiuh Wu	07/26/2004	Ju-Wang Hsu	07/26/2004
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Hun-Jan Tao	07/26/2004										
Tsang-Jiuh Wu	07/26/2004										
Ju-Wang Hsu	07/26/2004										
RECEIVING PARTY DATA											
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.										
Street Address:	No. 8, Li-Hsin Rd. 6										
Internal Address:	Science-Based Industrial Park										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10889416</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10889416						
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CORRESPONDENCE DATA											
Fax Number:	(214)200-0853										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	972-739-8631										
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NAME OF SUBMITTER:	David M. O'Dell										

CH \$40.00 10889416

Total Attachments: 3
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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|---|
| (1) | Ming-Huan Tsai | of | 8F, No. 41, Kwung-ming 6 th Rd., Jupei
Hsin-Chu, Taiwan 300, R.O.C. |
| (2) | Hun-Jan Tao | of | 13F, No. 17, Lane 175, Wu-Ling Rd.
Hsin-Chu, Taiwan 300, R.O.C. |
| (3) | Tsang-Jiuh Wu | of | No. 1, Lane 31, Huai-De Street
Taichung, Taiwan 300, R.O.C. |
| (4) | Ju-Wang Hsu | of | 4F1, No. 18, Lane 108, Leye Street, Daan Chiu
Taipei, Taiwan 106, R.O.C. |

have invented certain improvements in

BI-LEVEL RESIST STRUCTURE ND FABRICATION METHOD FOR CONTACT HOLES ON SEMICONDUCTOR SUBSTRATES

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on July 12, 2004, and assigned application number 10/889,416; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

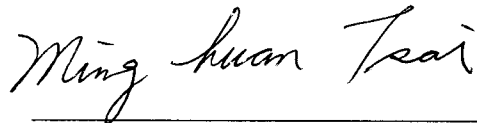
AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ming-Huan Tsai

Residence Address: 8F, No. 41, Kwung-ming 6th Rd., Jupei
Hsin-Chu, Taiwan 300, R.O.C.
Taiwan, R.O.C.

Dated: July 26, 2004

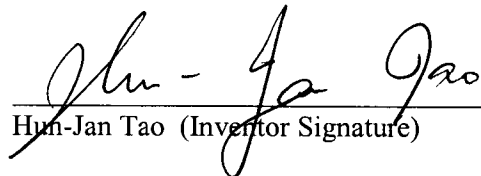


Ming-Huan Tsai (Inventor Signature)

Inventor Name: Hun-Jan Tao

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Hsin-Chu, Taiwan 300, R.O.C.
Taiwan, R.O.C.

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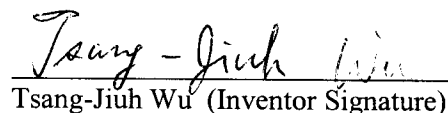


Hun-Jan Tao (Inventor Signature)

Inventor Name: Tsang-Jiuh Wu

Residence Address: No. 1, Lane 31, Huai-De Street
Taichung, Taiwan 300, R.O.C.
Taiwan, R.O.C.

Dated: July 26, 2004



Tsang-Jiuh Wu (Inventor Signature)

Inventor Name: Ju-Wang Hsu

Residence Address: 4F1, No. 18, Lane 108, Leye Street, Daan Chiu
Taipei, Taiwan 106, R.O.C.
Taiwan, R.O.C.

Dated: July 26, 2004

Ju-Wang Hsu
Ju-Wang Hsu (Inventor Signature)
